

**AMENDMENTS TO THE CLAIMS**

The following listing of Claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-13. (Withdrawn)

14. (currently amended) An electrical structure containing electrical connection members adapted for connecting to another electrical structure comprising:

- a first set of contacts in an electrical structure;
- at least one interface layer adhering to said set of contacts;
- a set of pads disposed over said set of contacts and including said interface layer;
- ~~a set of conductive pins adhered in situ to positioned on said pads, wherein said~~
- conductuve pins are formed as an integral part of said pads;
- a barrier layer adhering to all exposed surfaces of said set of pins; and
- a layer of solder surrounding the barrier layer.

15. (original) A structure according to claim 14, in which the material of the barrier layer blocks passage of material from the pins, thereby preventing the material from the pins from reacting with a constituent of the solder.

16. (original) A structure according to claim 14, in which the interface layer comprises a layer of adhesion material and a seed layer.

17. (original) A structure according to claim 15, in which the interface layer comprises a layer of adhesion material and a seed layer.

18. (currently amended) A structure according to claim 14, in which the interface layer includes material selected from the group ~~comprising~~ consisting of TiW, Ti, Ta, Cr and TaN.

19. (currently amended) A structure according to claim 15, in which the interface layer includes material selected from the group ~~comprising~~ consisting of TiW, Ti, Ta, Cr and TaN.

20. (currently amended) A structure according to claim 14, in which a wetting layer selected from the group ~~comprising~~ consisting of Cu and Au is formed on the barrier layer.

21. (currently amended) An electrical structure comprising:  
a plurality of contacts positioned on a top surface of said electrical structure;  
first and second interface layers positioned on said plurality of contacts;  
a plurality of pads in electrical communication with said plurality of contacts; and  
a plurality of electrical connection members plated directly onto said contacts,  
wherein said plurality of electrical connection members ~~are integral members~~ is formed as an integral component of said plurality of pads.

22. (previously presented) The electrical structure according to Claim 21, further comprising a barrier layer positioned about a first surface of said plurality of electrical connection members.

23. (previously presented) The electrical structure according to Claim 22, further comprising a layer of solder material positioned about said barrier layer.

24. (previously presented) The electrical structure according to Claim 22, wherein the barrier layer is adapted for containing said plurality of electrical connection members.

25. (previously presented) The electrical structure according to Claim 21, wherein said first and second interface layers comprise adhesive material and a seed layer.

26. (previously presented) The electrical structure according to Claim 21, wherein said first and second interface layers include a material selected from a group consisting of TiW, Ti, Ta, Cr, TaN, and a combination thereof.

27. (previously presented) The electrical structure according to Claim 21, further comprising a wetting layer formed about said barrier layer.

28. (previously presented) The electrical structure according to Claim 27, wherein said wetting layer is selected from a group consisting of Cu, Au and a combination thereof.